

**Features** (RoHS compliant)

Optically isolated

Low on-state resistance

Low input power consumption

MOSFET output thyristor

Ultra slim and light weight, Sil terminals type for high density mounting

Subminiature size 20.3 x 5.4 x 12.1(L x W x H)

**GENERAL DESCRIPTION****1. High capacity type power PhotoMOS.**

Can switch a wide range of currents and voltage. Can control various types of loads, from very small loads to a max,4.5A AC/DC current for sequencers, motors, and lamps.

**2. Low on-resistance and high sensitivity.**

Low on-resistance of less than Typ.0.035Ω (MISC1004)

High sensitivity LED operate current of Typ.3mA

**3. AC/DC dual use**

Bi-directional control is possible. There is no need to differentiate depending on the load as was necessary with the conventional SSR

**ABSOLUTE MAXIMUM RATINGS**

I/O isolation voltage	2500Vrms
Total power dissipation	1.6w
Ambient operating temperature range	-40°C to +85°C
Ambient storage temperature range	-40°C to +100°C
Ambient humidity	45% to 85% RH
Unit weight	Approx. 3g

**INPUT (TA=25°C)**

Item	Symbol	MISC1004(F)	MISC6501(F)	Remarks
LED Forward current	I <sub>F</sub>	50mA		
LED Reverse Voltage	V <sub>R</sub>	5V		
Peak forward current	I <sub>FP</sub>	1A		f=100Hz,Duty Ratio=0.1%
Power Dissipation	P <sub>In</sub>	75mW		

**OUTPUT (TA=25°C)**

Item	Symbol	MISC1004(F)	MISC6501(F)	Remarks
Load voltage (Peak AC)	V <sub>L</sub>	100V	650V	
Continuous load current	I <sub>L</sub>	4.5A	1.2A	Peak AC,DC
Peak load current	I <sub>peak</sub>	8A	3A	100ms(1 shot),VL=DC
Power Dissipation	P <sub>out</sub>	1.6W		

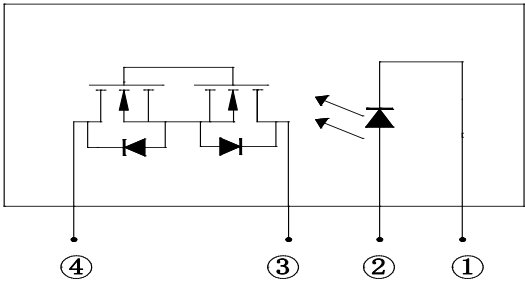
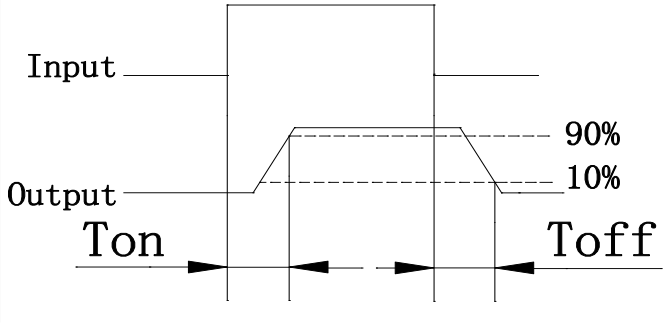
MISC

MASSUSE SOLID STATE RELAY

ELECTRIAL CHARACTERISTICS

item			Symbol	MISC1004(F)	MISC6501(F)	Condition
INPUT	LED Operate Current	Typical	I <sub>Fon</sub>	1.0mA		I <sub>L</sub> =100mA
		Max		3.0mA		V <sub>L</sub> =10V
	LED Turn off Current	min	I <sub>Foff</sub>	0.4mA		I <sub>L</sub> =100mA
		Typical		0.9mA		V <sub>L</sub> =10V
	LED Dropout Voltage	Typical	V <sub>F</sub>	1.25V		I <sub>F</sub> =50mA
		Max		1.5V		
OUTPUT	On resistance	Typical	R <sub>on</sub>	0.035Ω	0.4Ω	I <sub>F</sub> =10mA
		Max		0.06Ω	0.8Ω	I <sub>L</sub> =Max. Within 1s
	Off state leakage current	Max	I <sub>Leak</sub>	10μA		I <sub>F</sub> =0mA V <sub>L</sub> =Max
Transfer characteristics	Turn on time	Typical	T <sub>on</sub>	0.8ms		I <sub>F</sub> =10mA I <sub>L</sub> =100mA V <sub>L</sub> =10V
		Max		3ms		
	Turn off time	Typical	T <sub>off</sub>	0.1ms		
		Max		1ms		
	I/O Capacitance	Typical	C <sub>iso</sub>	0.8pF		f=1MHz
		Max		1.5pF		V <sub>B</sub> =0V
	Initial I/O isolation resistance	Mix	R <sub>iso</sub>	1000MΩ		500VDC
Max. Operating frequency	Max	---	0.5cps		I <sub>F</sub> =10mA Duty factor=50% I <sub>L</sub> =Max, V <sub>L</sub> =Max	

Turn on/Turn off time and PIN Configuration

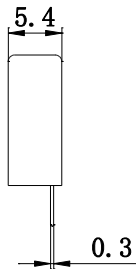
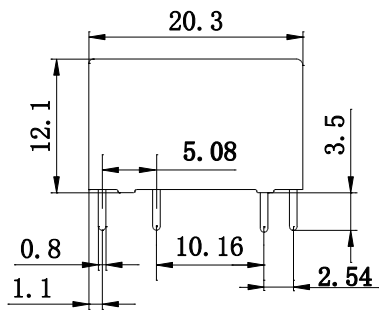


- MISCXXXX
1. INPUT:DC -  
2. INPUT:DC +  
3. OUTPUT:DC/AC  
4. OUTPUT:DC/AC
- MISCXXXX (F)
1. INPUT:DC +  
2. INPUT:DC -  
3. OUTPUT:DC/AC  
4. OUTPUT:DC/AC

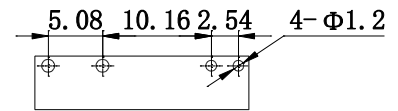
## OUTLINE DIMENSIONS, WIRING DIAGRAM AND PC BOARD LAYOUT

Unit: mm

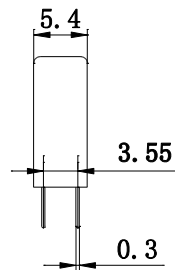
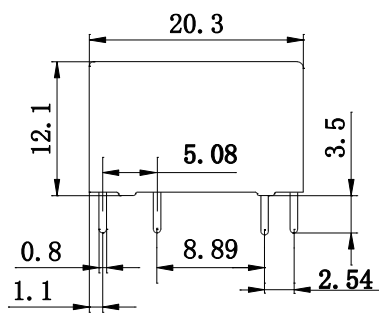
MISCXXXX



PCB LAYOUT



MISCXXXX (F)



PCB LAYOUT

